NEWS RELEASE

TE Connectivity Debuts ChipConnect Cable Assemblies

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New Cable Assembly Enables Intel® Omni-Path Architecture

HARRISBURG, Pa., Aug. 3, 2017 /PRNewswire/ -- TE Connectivity (TE), a world leader in connectivity and sensors, announced today its new ChipConnect internal faceplate-to-processor (IFP) cable assemblies. Designed for Intel Omni-Path Architecture (OPA), TE's ChipConnect assemblies mate directly with LGA 3647 sockets at the processor and Intel Omni-Path internal faceplate transition (IFT) ports at the faceplate for 25 Gbps speeds. These new cable assemblies reduce system design time and costs by eliminating the need to use costlier, lower-loss printed circuit board (PCB) materials and associated re-timers to route signal. System design is made easier by reducing the complexity of PCB laminates and routing.

ChipConnect assemblies are available in standard lengths and breakouts, and they can also be customized for specific applications. The new cable assemblies provide 4X and 8X high-speed data transmission lanes, and offer straight and right-angle (left/right exit) linear edge connector (LEC) cable plugs to accommodate cable routing. In addition to these cable assemblies, TE offers compatible LGA 3647 sockets and hardware (Socket P0 and P1). TE is currently one of a limited number of Intel qualified suppliers offering these first-generation IFP cable assemblies and is also a development partner for future generation cable assembly designs for Intel OPA.

"Intel's OPA design is a standard in the industry, and our ChipConnect products deliver greater design flexibility and higher performance in these applications," said Ann Ou, product manager for TE Connectivity's Data and Devices business unit. "With this product, TE becomes a one-stop source for OPA-compliant sockets and cable assemblies."

For more information, visit **www.te.com/chipconnect**

ABOUT TE CONNECTIVITY

TE Connectivity (NYSE: TEL) is a $12 billion global technology leader. Our commitment to innovation enables advancements in transportation, industrial applications, medical technology, energy, data communications, and the home. TE's unmatched breadth of connectivity and sensor solutions, proven in the harshest of environments, helps build a safer, greener, smarter and more connected world. With 75,000 people – including more than 7,000 engineers – working alongside customers in nearly 150 countries, we help ensure that EVERY CONNECTION COUNTS – **www.TE.com**.

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